OSRAM LA G6SP.02 **Datasheet**



Advanced Power TOPLED®

LA G6SP.02

The Advanced Power TOPLED.02 (APT.02) features ams OSRAM's state-of-the-art generation of PLCC 6 packages, which have set a market standard in the mid power LED world and were decades ago the first of its kind. With its very robust design, the APT.02 family can withstand harsh environmental conditions and offers the highest level of processability. Containing our latest InGaAIP-chip technology the APT.02 keeps its market leading brightness performance and offers a wide range of available bins with a high luminous efficiency and an excellent thermal resistance.





Applications

- Static Signaling

Features

- Package: white SMT package, colorless clear silicone resin
- Chip technology: Thinfilm
- Typ. Radiation: 120° (Lambertian emitter)
- Color: λ_{dom} = 617 nm (• amber)
- Corrosion Robustness Class: 3B
- Qualifications: AEC-Q102 Qualified with RV-level 1
- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)





| Ordoring | Information |
|----------|--------------------|
| Ordering | mulandi |

Ordering Code Type Luminous Intensity 1)

 $I_{F} = 140 \text{ mA}$ $I_{_{_{V}}}$

LA G6SP.02-7E6F-24-G3R3-140 9.0 ... 14.0 cd Q65113A3564



| Maximum Ratings | | | |
|--|-----------------|------|---------|
| Parameter | Symbol | | Values |
| Operating Temperature | T _{op} | min. | -40 °C |
| | op. | max. | 125 °C |
| Storage Temperature | T_{stg} | min. | -40 °C |
| | otg | max. | 125 °C |
| Junction Temperature 2) | T _i | max. | 135 °C |
| Junction Temperature for short time applications* | T _i | max. | 150 °C |
| Forward current | I _F | min. | 5 mA |
| $T_S = 25 ^{\circ}C$ | • | max. | 200 mA |
| Forward current pulsed | F pulse | max. | 1000 mA |
| $t \le 10 \mu\text{s}; \text{ D} \le 0.005 ; \text{ T}_{\text{s}} = 25 ^{\circ}\text{C}$ | , paice | | |
| Reverse voltage 3) | V_R | max. | 12 V |
| $T_S = 25 ^{\circ}\text{C}$ | IX | | |
| ESD withstand voltage | V_{ESD} | | 2 kV |
| acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2) | 200 | | |

^{*} The median lifetime (L70/B50) for Tj = 150°C is 100h.



Characteristics

 $I_F = 140 \text{ mA}; T_S = 25 \text{ }^{\circ}\text{C}$

| Parameter | Symbol | | Values |
|--|-----------------------------|------|----------|
| Peak Wavelength | $oldsymbol{\lambda}_{peak}$ | typ. | 624 nm |
| Dominant Wavelength 4) | $\lambda_{\sf dom}$ | min. | 612 nm |
| $I_{\rm F} = 140 \text{ mA}$ | dom | typ. | 617 nm |
| | | max. | 624 nm |
| Spectral Bandwidth at 50% I _{rel,max} | Δλ | typ. | 18 nm |
| Viewing angle at 50% $\rm I_{\rm v}$ | 2φ | typ. | 120 ° |
| Forward Voltage 5) | V_{F} | min. | 1.90 V |
| $I_{\rm F} = 140 \text{ mA}$ | • | typ. | 2.25 V |
| | | max. | 2.50 V |
| Reverse current 3) | I _R | typ. | 0.01 μΑ |
| V _R = 12 V | TX | max. | 10 µA |
| Real thermal resistance junction/solderpoint ⁶⁾ | R _{thJS real} | typ. | 38 K / W |
| | thos real | max. | 50 K / W |
| Electrical thermal resistance junction/solderpoint ⁶⁾ | R _{thJS elec.} | typ. | 23 K / W |
| with efficiency η_e = 39 % | tiloo elec. | max. | 31 K / W |



Brightness Groups

| Group | Luminous Intensity ¹⁾ I _F = 140 mA min. I _v | Luminous Intensity. 1) I _F = 140 mA max. I _v | Luminous Flux 7) $I_F = 140 \text{ mA}$ $typ.$ Φ_V |
|-------|--|---|---|
| 7E | 9.0 cd | 10.0 cd | 28.5 lm |
| 8E | 10.0 cd | 11.2 cd | 31.8 lm |
| 5F | 11.2 cd | 12.5 cd | 35.6 lm |
| 6F | 12.5 cd | 14.0 cd | 39.8 lm |

Forward Voltage Groups

| Group | Forward Voltage ⁵⁾ I _F = 140 mA min. V _F | Forward Voltage ⁵⁾ I _F = 140 mA max. V _F | |
|-------|---|---|--|
| G3 | 1.90 V | 2.05 V | |
| K3 | 2.05 V | 2.20 V | |
| N3 | 2.20 V | 2.35 V | |
| R3 | 2.35 V | 2.50 V | |

Wavelength Groups

| Group Dominant Wavelength ⁴⁾ $I_{F} = 140 \text{ mA}$ | | Dominant Wavelength ⁴⁾ I _F = 140 mA | |
|--|---------------------|---|--|
| | min. | max. | |
| | $\lambda_{\sf dom}$ | $\lambda_{\sf dom}$ | |
| 2 | 612 nm | 616 nm | |
| 3 | 616 nm | 620 nm | |
| 4 | 620 nm | 624 nm | |

LA G6SP.02 DATASHEET



Group Name on Label

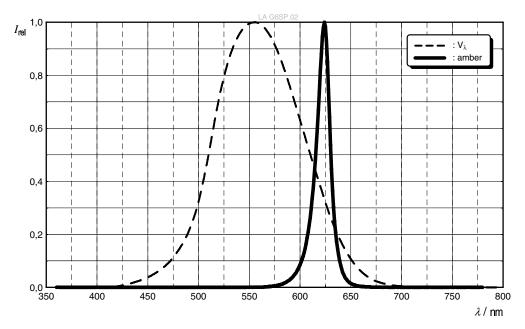
Example: 5F-2-G3

| Brightness | Wavelength | Forward Voltage |
|------------|------------|-----------------|
| 5F | 2 | G3 |



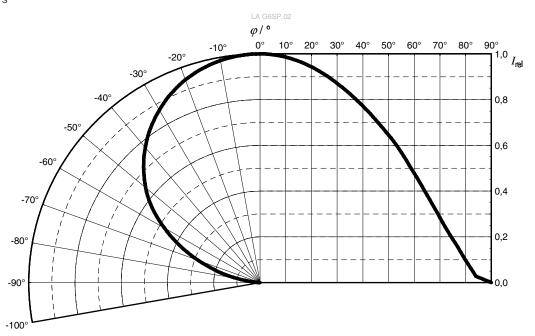
Relative Spectral Emission 7)

 I_{rel} = f (λ); I_{F} = 140 mA; T_{S} = 25 °C



Radiation Characteristics 7)

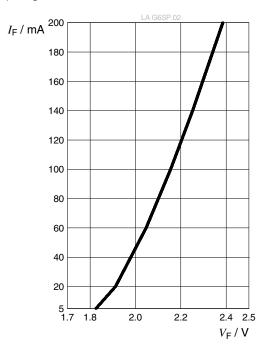
 $I_{rel} = f(\phi); T_S = 25 °C$





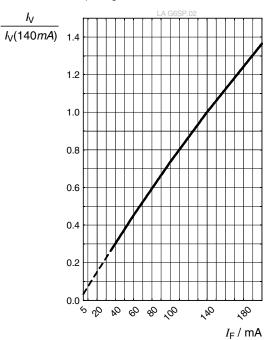
Forward current 7)

$$I_F = f(V_F); T_S = 25 \, ^{\circ}C$$



Relative Luminous Intensity 7), 8)

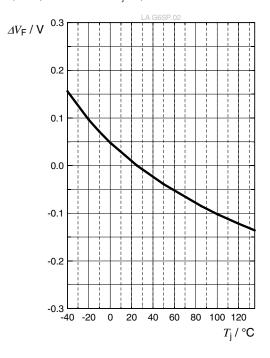
$$I_{v}/I_{v}(140 \text{ mA}) = f(I_{F}); T_{S} = 25 \text{ °C}$$





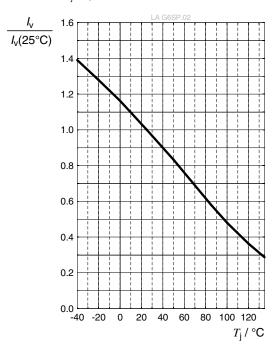
Forward Voltage 7)

$$\Delta V_{_F} = V_{_F} - V_{_F} (25 \ ^{\circ}C) = f(T_{_j}); \ I_{_F} = 140 \ mA$$



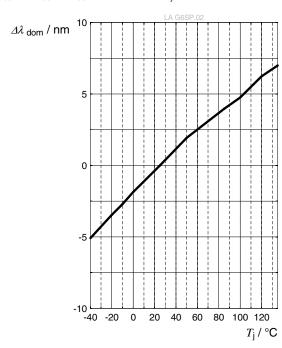
Relative Luminous Intensity 7)

$$I_{v}/I_{v}(25 \text{ °C}) = f(T_{i}); I_{F} = 140 \text{ mA}$$



Dominant Wavelength 7)

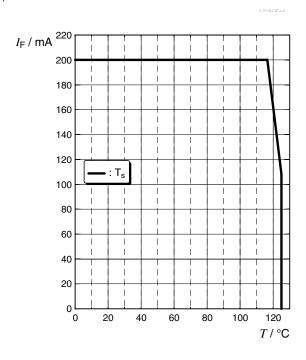
$$\Delta \lambda_{\text{dom}} = \lambda_{\text{dom}} - \lambda_{\text{dom}} (25 \text{ °C}) = \text{f(T}_{\text{j}}); \text{ I}_{\text{F}} = 140 \text{ mA}$$





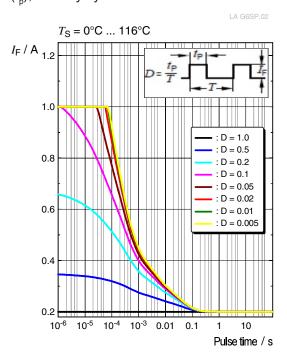
Max. Permissible Forward Current 6)

 $I_{\scriptscriptstyle F} = f(T)$



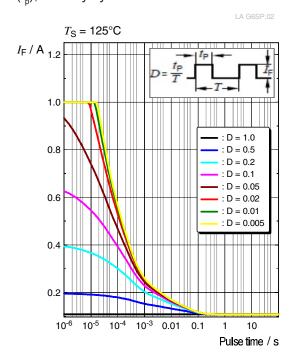
Permissible Pulse Handling Capability

 $I_F = f(t_p)$; D: Duty cycle



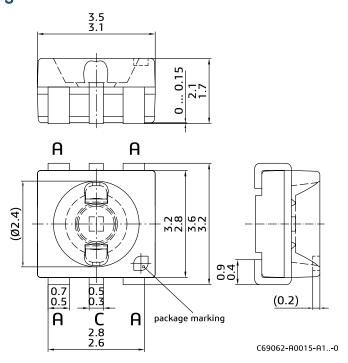
Permissible Pulse Handling Capability

 $I_F = f(t_p)$; D: Duty cycle





Dimensional Drawing 9)



Further Information:

Approximate Weight: 40.0 mg

Package marking: Cathode

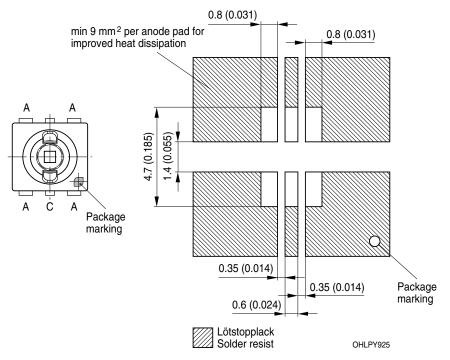
Corrosion test: Class: 3B

Test condition: 40°C / 90 % RH / 15 ppm H₂S / 14 days (stricter than IEC

60068-2-43)



Recommended Solder Pad 9)

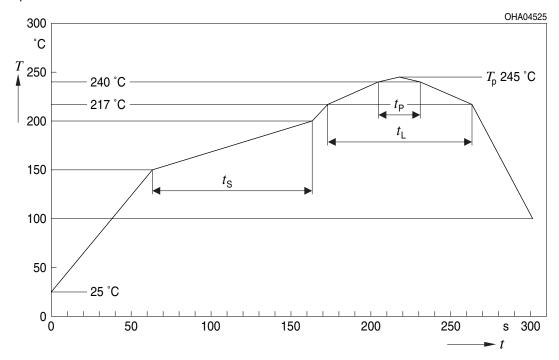


For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere. Package not suitable for ultra sonic cleaning.



Reflow Soldering Profile

Product complies to MSL Level 2 acc. to JEDEC J-STD-020E



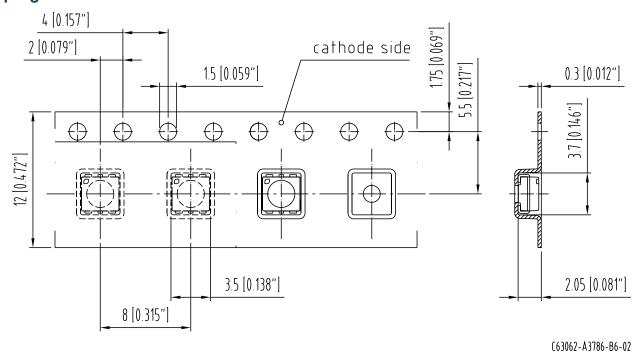
| Profile Feature | Symbol | Pb-Free (SnAgCu) Assembly | | Unit | |
|--|--------------------------------|---------------------------|----------------|---------|-----|
| | | Minimum | Recommendation | Maximum | |
| Ramp-up rate to preheat*) | ' | | 2 | 3 | K/s |
| 25 °C to 150 °C | | | | | |
| Time t _s | t _s | 60 | 100 | 120 | S |
| T_{Smin} to T_{Smax} | | | | | |
| Ramp-up rate to peak*) | | | 2 | 3 | K/s |
| T_{Smax} to T_{P} | | | | | |
| Liquidus temperature | T_{L} | | 217 | | °C |
| Time above liquidus temperature | $t_{\scriptscriptstyle \perp}$ | | 80 | 100 | S |
| Peak temperature | T _P | | 245 | 260 | °C |
| Time within 5 °C of the specified peak | t _P | 10 | 20 | 30 | S |
| temperature T _P - 5 K | | | | | |
| Ramp-down rate* | | | 3 | 6 | K/s |
| T _P to 100 °C | | | | | |
| Time | | | | 480 | S |
| 25 °C to T _P | | | | | |

All temperatures refer to the center of the package, measured on the top of the component

^{*} slope calculation DT/Dt: Dt max. 5 s; fulfillment for the whole T-range

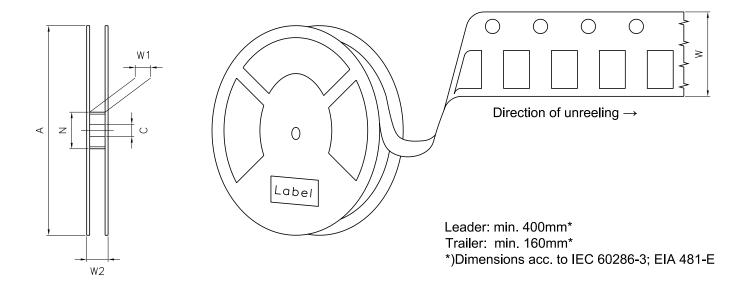


Taping 9)





Tape and Reel 10)

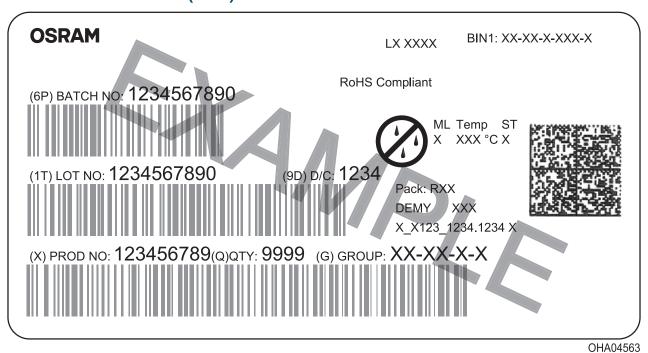


Reel Dimensions

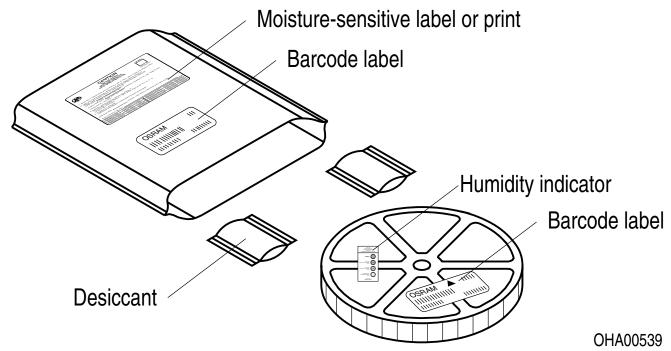
| Α | W | N_{\min} | W ₁ | $W_{2 \text{max}}$ | Pieces per PU |
|--------|---------------------|------------|----------------|---------------------|---------------|
| 180 mm | 12 + 0.3 / - 0.1 mm | 60 mm | 12.4 + 2 mm | 18.4 mm | 1000 |
| 330 mm | 12 + 0.3 / - 0.1 mm | 60 mm | 12.4 + 2 mm | 18.4 mm | 4000 |



Barcode-Product-Label (BPL)



Dry Packing Process and Materials 9)



Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.



Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet fall into the class exempt group (exposure time 10000 s). Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related information please visit https://ams-osram.com/support/application-notes



Disclaimer

Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on our website.

Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Product and functional safety devices/applications or medical devices/applications

Our components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

Our products are not qualified at module and system level for such application.

In case buyer – or customer supplied by buyer – considers using our components in product safety devices/ applications or medical devices/applications, buyer and/or customer has to inform our local sales partner immediately and we and buyer and /or customer will analyze and coordinate the customer-specific request between us and buyer and/or customer.



Glossary

- Brightness: Brightness values are measured during a current pulse of typically 25 ms, with an internal reproducibility of ±8 % and an expanded uncertainty of ±11 % (acc. to GUM with a coverage factor of k = 3).
- Package discoloration: The LED chip exhibits excellent performance but slight package discoloration occurs at highest temperatures.
- 3) Reverse Operation: This product is intended to be operated applying a forward current within the specified range. Applying any continuous reverse bias or forward bias below the voltage range of light emission shall be avoided because it may cause migration which can change the electro-optical characteristics or damage the LED.
- Wavelength: The wavelength is measured at a current pulse of typically 25 ms, with an internal reproducibility of ±0.5 nm and an expanded uncertainty of ±1 nm (acc. to GUM with a coverage factor of k = 3).
- Forward Voltage: The forward voltage is measured during a current pulse of typically 8 ms, with an internal reproducibility of ±0.05 V and an expanded uncertainty of ±0.1 V (acc. to GUM with a coverage factor of k = 3).
- 6) Thermal Resistance: Rth max is based on statistic values (6σ) used for Derating.
- Typical Values: Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- Characteristic curve: In the range where the line of the graph is broken, you must expect higher differences between single devices within one packing unit.
- Tolerance of Measure: Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.
- Tape and Reel: All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.

LA G6SP.02 DATASHEET



Revision History

| Version | Date | Change |
|---------|------------|------------------------------|
| 1.0 | 2022-03-17 | Initial Version |
| 1.1 | 2024-03-19 | Applications Reel Dimensions |



EU RoHS and China RoHS compliant product 此产品符合欧盟 RoHS 指令的要求; 按照中国的相关法规和标准, 不含有毒有害物质或元素。

Published by ams-OSRAM AG

Tobelbader Strasse 30, 8141 Premstaetten, Austria Phone +43 3136 500-0 ams-osram.com © All rights reserved





Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

ams OSRAM:

LA G6SP.02-7E6F-24-G3R3-140